Static Electrical Characteristics @ $T_J = 25$ °C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	100			V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient		0.088		V/°C	Reference to 25°C, I _D = 1mA
R _{DS(on)}	Static Drain-to-Source On-Resistance		15	18	mΩ	V _{GS} = 10V, I _D = 33A ③
$V_{GS(th)}$	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
gfs	Forward Transconductance	39			S	$V_{DS} = 25V, I_{D} = 33A$
I _{DSS}	Drain-to-Source Leakage Current			20	μA	$V_{DS} = 100V, V_{GS} = 0V$
				250	İ	$V_{DS} = 100V, V_{GS} = 0V, T_{J} = 125^{\circ}C$
I _{GSS}	Gate-to-Source Forward Leakage			200	nA	V _{GS} = 20V
	Gate-to-Source Reverse Leakage			-200	İ	V _{GS} = -20V

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions	
Q_g	Total Gate Charge		69	100		$I_D = 33A$	
Q_{gs}	Gate-to-Source Charge		15		nC	$V_{DS} = 80V$	
Q_{gd}	Gate-to-Drain ("Miller") Charge		25		İ	V _{GS} = 10V ③	
t _{d(on)}	Turn-On Delay Time		14			$V_{DD} = 50V$	
t _r	Rise Time		43		İ	$I_D = 33A$	
t _{d(off)}	Turn-Off Delay Time		53		ns	$R_G = 6.8 \Omega$	
t _f	Fall Time		42			V _{GS} = 10V ③	
L _D	Internal Drain Inductance		4.5			Between lead,	
					nH	6mm (0.25in.)	
L _S	Internal Source Inductance		7.5		l	from package	
						and center of die contact	
C _{iss}	Input Capacitance		2930			$V_{GS} = 0V$	
C _{oss}	Output Capacitance		290			$V_{DS} = 25V$	
C _{rss}	Reverse Transfer Capacitance		180		pF	f = 1.0MHz	
C _{oss}	Output Capacitance		1200			$V_{GS} = 0V, V_{DS} = 1.0V, f = 1.0MHz$	
C _{oss}	Output Capacitance		180			$V_{GS} = 0V, V_{DS} = 80V, f = 1.0MHz$	
C _{oss} eff.	Effective Output Capacitance		430			$V_{GS} = 0V, V_{DS} = 0V \text{ to } 80V $	

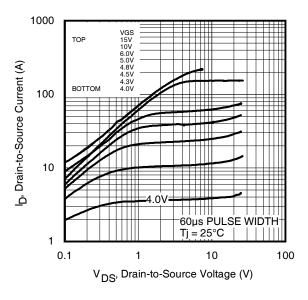
Diode Characteristics

Biode Characteriotics						
	Parameter	Min.	Тур.	Max.	Units	Conditions
IS	Continuous Source Current			56		MOSFET symbol
	(Body Diode)				Α	showing the
I _{SM}	Pulsed Source Current			220		integral reverse
	(Body Diode) ①					p-n junction diode.
V_{SD}	Diode Forward Voltage			1.3	V	$T_J = 25^{\circ}C$, $I_S = 33A$, $V_{GS} = 0V$ ③
t _{rr}	Reverse Recovery Time		35	53	ns	$T_J = 25^{\circ}C, I_F = 33A, V_{DD} = 50V$
Q _{rr}	Reverse Recovery Charge		41	62	nC	di/dt = 100A/µs ③
t _{on}	Forward Turn-On Time	Intrinsio	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)			

Qualification Information[†]

Qualification Level		Automotive (per AEC-Q101) ††				
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.				
Moisture Sensitivity Level		D-PAK	MSL1			
	Machine Model	Class M4				
		AEC-Q101-002				
	Human Body Model	Class H1C				
ESD		AEC-Q101-001				
	Charged Device	Class C3				
	Model	AEC-Q101-005				
RoHS Compliant		Yes				

- † Qualification standards can be found at International Rectifier's web site: http://www.irf.com/
- †† Exceptions to AEC-Q101 requirements are noted in the qualification report.



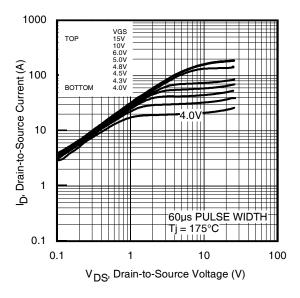
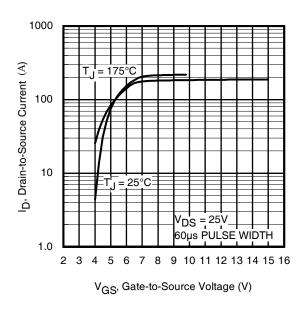


Fig 1. Typical Output Characteristics

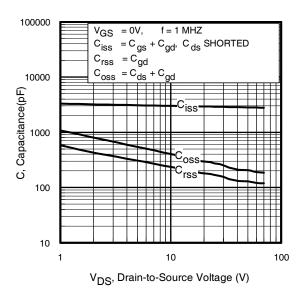
Fig 2. Typical Output Characteristics



100 G_{fs}, Forward Transconductance (S) $T_J = 25^{\circ}C$ 80 60 $T_{J} = 175^{\circ}C$ 40 20 $V_{DS} = 10V$ 0 0 10 20 50 70 80 30 40 60 I_D , Drain-to-Source Current (A)

Fig 3. Typical Transfer Characteristics

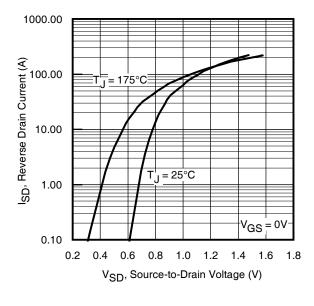
Fig 4. Typical Forward Transconductance vs. Drain Current



12.0 I_D= 33A 10.0 V_{GS}, Gate-to-Source Voltage (V) $V_{\overline{DS}} = 80V$ $V_{DS} = 50V$ V_{DS}= 20V 8.0 6.0 4.0 2.0 0.0 10 30 40 50 60 70 80 0 Q_G Total Gate Charge (nC)

Fig 5. Typical Capacitance vs. Drain-to-Source Voltage

Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage



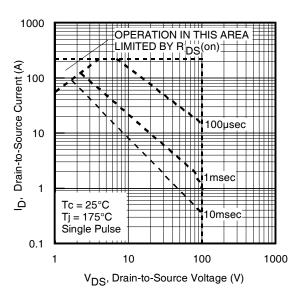
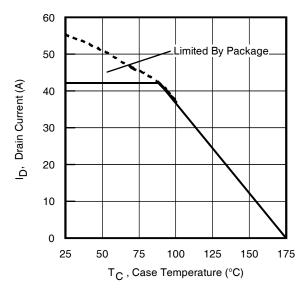


Fig 7. Typical Source-Drain Diode Forward Voltage

Fig 8. Maximum Safe Operating Area

nce



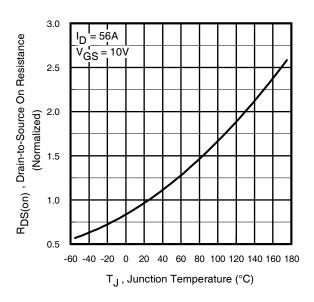


Fig 9. Maximum Drain Current vs. Case Temperature

Fig 10. Normalized On-Resistance vs. Temperature

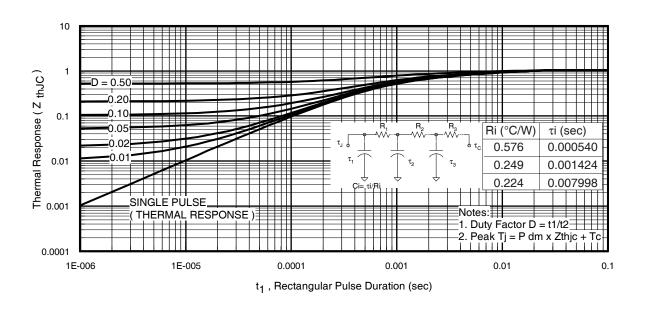


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

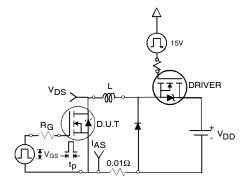


Fig 12a. Unclamped Inductive Test Circuit

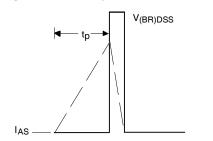


Fig 12b. Unclamped Inductive Waveforms

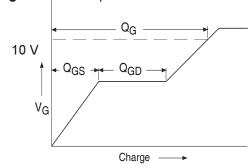


Fig 13a. Basic Gate Charge Waveform

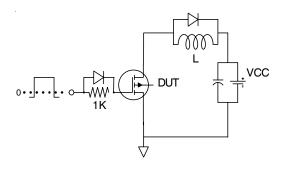


Fig 13b. Gate Charge Test Circuit www.irf.com

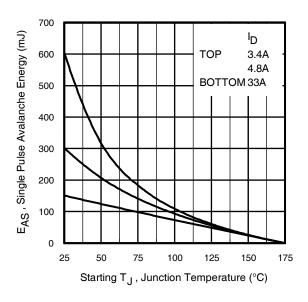


Fig 12c. Maximum Avalanche Energy vs. Drain Current

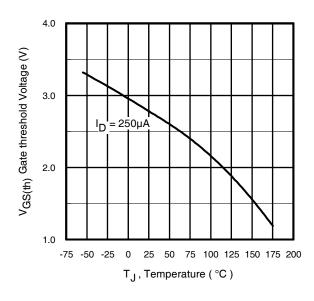


Fig 14. Threshold Voltage vs. Temperature

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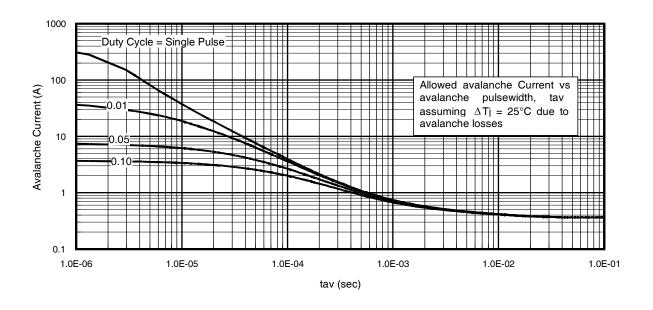


Fig 15. Typical Avalanche Current vs. Pulsewidth

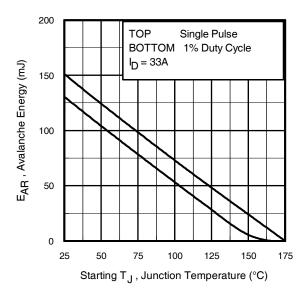


Fig 16. Maximum Avalanche Energy vs. Temperature

Notes on Repetitive Avalanche Curves, Figures 15, 16: (For further info, see AN-1005 at www.irf.com)

- Avalanche failures assumption:
 Purely a thermal phenomenon and failure occurs at a temperature far in excess of T_{jmax}. This is validated for every part type.
- 2. Safe operation in Avalanche is allowed as long asT_{jmax} is not exceeded.
- 3. Equation below based on circuit and waveforms shown in Figures 12a, 12b.
- 4. $P_{D (ave)}$ = Average power dissipation per single avalanche pulse.
- BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
- 6. I_{av} = Allowable avalanche current.
- 7. ΔT = Allowable rise in junction temperature, not to exceed T_{jmax} (assumed as 25°C in Figure 15, 16). t_{av} = Average time in avalanche.

 $D = Duty cycle in avalanche = t_{av} \cdot f$

 $Z_{th,JC}(D, t_{av})$ = Transient thermal resistance, see figure 11)

$$\begin{split} P_{D\;(ave)} &= 1/2\;(\;1.3 \cdot BV \cdot I_{av}) = \Delta T/\;Z_{thJC} \\ I_{av} &= 2\Delta T/\;[1.3 \cdot BV \cdot Z_{th}] \\ E_{AS\;(AR)} &= P_{D\;(ave)} \cdot t_{av} \end{split}$$

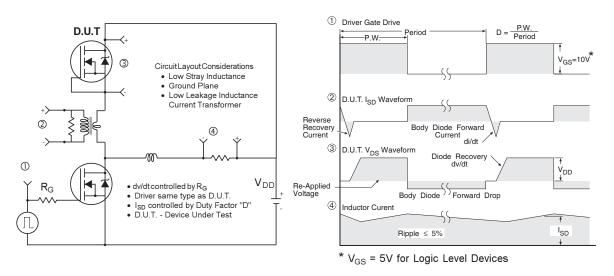


Fig 17. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs

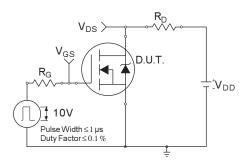


Fig 18a. Switching Time Test Circuit

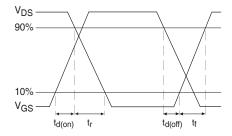
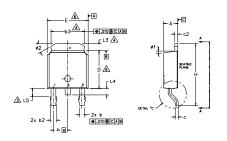
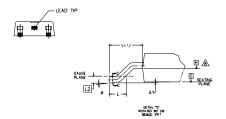


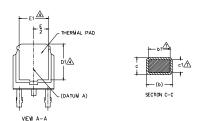
Fig 18b. Switching Time Waveforms

D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)







- 1.- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2.- DIMENSION ARE SHOWN IN INCHES [MILLIMETERS].
- LEAD DIMENSION UNCONTROLLED IN L5.

 DIMENSION D1, E1, L3 & b3 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
- A_→ DIMENSION DI, ET, L3 & BS ESTABLISH A WINNIMUM MOUNTING SUPFACE FOR THERMAL PAD.

 5.— SECTION, CC—O DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND 0.10

 [0.13 AND 0.25] FROM THE LEAD TIP.

 Δ→ DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE WEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.

 Δ→ DIMENSION b1 & c1 APPLIED TO BASE METAL ONLY.
- A- DATUM A & B TO BE DETERMINED AT DATUM PLANE H.

 9.- OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

S Y M	DIMENSIONS				
B	B MILLIMETERS		INC	Ō	
O L	MIN.	MAX.	MIN.	MAX.	E S
Α	2.18	2.39	.086	.094	
A1	-	0.13	-	.005	
ь	0.64	0.89	.025	.035	
ь1	0.65	0.79	.025	.031	7
b2	0.76	1.14	.030	.045	
b3	4,95	5.46	,195	.215	4
c	0.46	0.61	.018	.024	
¢1	0.41	0.56	.016	.022	7
c2	0,46	0.89	,018	,035	
D	5,97	6,22	.235	.245	6
D1	5.21	-	.205	-	4
Ε	6.35	6.73	.250	.265	6
E1	4.32	-	.170	-	4
e	2.29	BSC	.090	BSC	
н	9.40	10.41	.370	.410	
L	1.40	1.78	.055	.070	
L1	2,74	BSC	.108 REF.		
L2	0.51	BSC	.020 BSC		
L3	0.89	1,27	.035	.050	4
L4	-	1.02	-	.040	
L5	1,14	1,52	.045	,060	3
ø	0.	10°	0,	10*	
ø1	0.	15*	0.	15*	
ø2	25	35*	25*	35*	

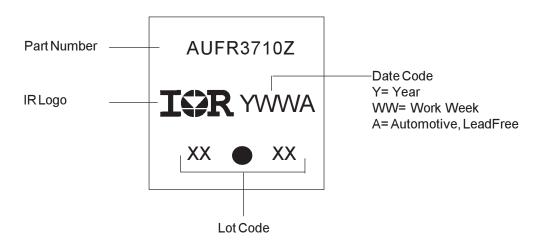
LEAD ASSIGNMENTS

<u>HEXFE T</u>

IGBT & CoPAK

- 1.- GATE
 2.- COLLECTOR
 3.- EMITTER
 4.- COLLECTOR

D-Pak Part Marking Information

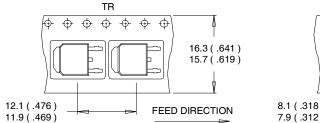


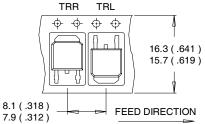
Note: For the most current drawing please refer to IR website at http://www.irf.com/package/

AUIRFR3710Z

D-Pak (TO-252AA) Tape & Reel Information

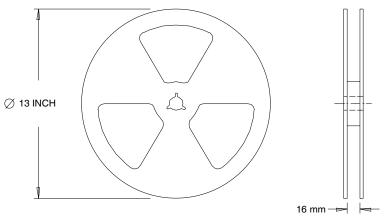
Dimensions are shown in millimeters (inches)





NOTES:

- 1. CONTROLLING DIMENSION: MILLIMETER.
- 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
- 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES:

1. OUTLINE CONFORMS TO EIA-481.

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11).
- $R_G = 25\Omega$, $I_{AS} = 33A$, $V_{GS} = 10V$. Part not recommended for use above this value.
- ④ Coss eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .
- S Limited by T_{Jmax}, see Fig.12a, 12b, 15, 16 for typical repetitive avalanche performance.
- ② Limited by T_{Jmax} , starting $T_J = 25$ °C, L = 0.28mH ⑥ This value determined from sample failure population, starting $T_J = 25$ °C, L = 0.28mH, $R_G = 25\Omega$, $I_{AS} = 33$ A, $V_{GS} = 10$ V.
 - ① When mounted on 1" square PCB (FR-4 or G-10 Material) . For recommended footprint and soldering techniques refer to application note #AN-994.
 - ® R_A is measured at TJ approximately 90°C.

Ordering Information

Base part	Package Type	Standard Pack	Complete Part Number	
		Form	Quantity	
AUIRFR3710Z	Dpak	Tube	75	AUIRFR3710Z
		Tape and Reel	2000	AUIRFR3710ZTR
		Tape and Reel Left	3000	AUIRFR3710ZTRL
		Tape and Reel Right	3000	AUIRFR3710ZTRR

AUIRFR3710Z

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